

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																						
NATURE OF CONVEYANCE:	ASSIGNMENT																						
CONVEYING PARTY DATA																							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yaojian Lin</td> <td>01/12/2012</td> </tr> <tr> <td>Pandi C. Marimuthu</td> <td>01/12/2012</td> </tr> <tr> <td>Kang Chen</td> <td>01/12/2012</td> </tr> <tr> <td>Hin Hwa Goh</td> <td>01/12/2012</td> </tr> <tr> <td>Yu Gu</td> <td>01/13/2012</td> </tr> <tr> <td>Il Kwon Shim</td> <td>01/12/2012</td> </tr> <tr> <td>Rui Huang</td> <td>01/12/2012</td> </tr> <tr> <td>Seng Guan Chow</td> <td>01/12/2012</td> </tr> <tr> <td>Jianmin Fang</td> <td>01/05/2012</td> </tr> <tr> <td>Xia Feng</td> <td>01/06/2012</td> </tr> </tbody> </table>		Name	Execution Date	Yaojian Lin	01/12/2012	Pandi C. Marimuthu	01/12/2012	Kang Chen	01/12/2012	Hin Hwa Goh	01/12/2012	Yu Gu	01/13/2012	Il Kwon Shim	01/12/2012	Rui Huang	01/12/2012	Seng Guan Chow	01/12/2012	Jianmin Fang	01/05/2012	Xia Feng	01/06/2012
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Xia Feng	01/06/2012																						
RECEIVING PARTY DATA																							
Name:	STATS ChipPAC, Ltd.																						
Street Address:	10 Ang Mo Kio Street 65																						
Internal Address:	#05-17/20 Techpoint																						
City:	Singapore																						
State/Country:	SINGAPORE																						
Postal Code:	569059																						
PROPERTY NUMBERS Total: 1																							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13333739</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13333739																		
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Application Number:	13333739																						
CORRESPONDENCE DATA																							
Fax Number:	(480)499-9456																						
Phone:	480-499-9400																						
Email:	main@plgaz.com																						
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>																							

OP \$40.00 13333739

Correspondent Name: PATENT LAW GROUP
Address Line 1: 605 W. Knox Road
Address Line 2: Suite 104
Address Line 4: Tempe, ARIZONA 85284

ATTORNEY DOCKET NUMBER:	2515.0323
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NAME OF SUBMITTER:	Robert D. Atkins
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Total Attachments: 10
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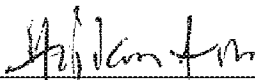
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER DISPOSED OVER THE SEMICONDUCTOR DIE FOR STRESS RELIEF, which is described, illustrated, and claimed in United States Application No. 13/333,739, filed December 21, 2011, United States Provisional Application No. 61/435,223, filed January 21, 2011, and United States Provisional Application No. 61/443,157, filed February 15, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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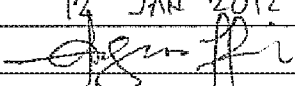
Signature for YAOJIAN LIN

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

12 JAN 2012

DIOS CORO MERLO
5 YISHUN STREET 23
SINGAPORE 768442

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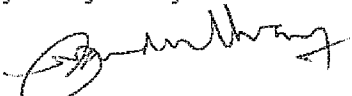
For good and valuable consideration, the receipt of which is hereby acknowledged, I, PANDI C. MARIMUTHU of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER DISPOSED OVER THE SEMICONDUCTOR DIE FOR STRESS RELIEF, which is described, illustrated, and claimed in United States Application No. 13/333,739, filed December 21, 2011, United States Provisional Application No. 61/435,223, filed January 21, 2011, and United States Provisional Application No. 61/443,157, filed February 15, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for PANDI C. MARIMUTHU

Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

12 JAN 2012

Dioscoro Merilo

5 YISHUN STREET 23

SINGAPORE 768442

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For good and valuable consideration, the receipt of which is hereby acknowledged, I, KANG CHEN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER DISPOSED OVER THE SEMICONDUCTOR DIE FOR STRESS RELIEF, which is described, illustrated, and claimed in United States Application No. 13/333,739, filed December 21, 2011, United States Provisional Application No. 61/435,223, filed January 21, 2011, and United States Provisional Application No. 61/443,157, filed February 15, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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chen kang
Signature for KANG CHEN

Witnessed on this date: 12 JAN. 2012
Signature of Witness: [Signature]
Printed Name of Witness: DIOSCORDO MERILLO
Address of Witness: 5 YISHUN STREET 23
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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HIN HWA GOH of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER DISPOSED OVER THE SEMICONDUCTOR DIE FOR STRESS RELIEF, which is described, illustrated, and claimed in United States Application No. 13/333,739, filed December 21, 2011, United States Provisional Application No. 61/435,223, filed January 21, 2011, and United States Provisional Application No. 61/443,157, filed February 15, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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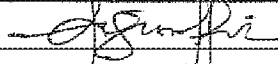


Signature for HIN HWA GOH

Witnessed on this date:

12 JAN. 2012

Signature of Witness:



Printed Name of Witness:

DIOSCORO MERILO

Address of Witness:

5 YISHUN STREET 23

SINGAPORE 768442

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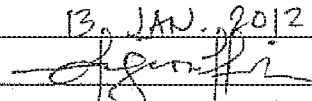
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Signature for YU GU

Witnessed on this date: _____
Signature of Witness:  _____
Printed Name of Witness: _____
Address of Witness: _____
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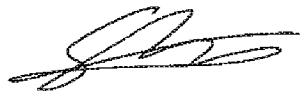
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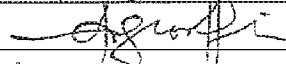


Signature for IL KWON SHIM

Witnessed on this date:

12 JAN 2012

Signature of Witness:



Printed Name of Witness:

DIOS CORO MERLO

Address of Witness:

5 YLSTON STREET 23
SINGAPORE 768442

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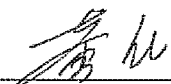
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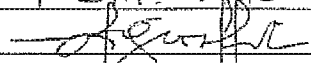


Signature for RUI HUANG

Witnessed on this date:

12 JAN. 2012

Signature of Witness:



Printed Name of Witness:

DUSCO TO MERLO

Address of Witness:

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SENG GUAN CHOW of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER DISPOSED OVER THE SEMICONDUCTOR DIE FOR STRESS RELIEF, which is described, illustrated, and claimed in United States Application No. 13/333,739, filed December 21, 2011, United States Provisional Application No. 61/435,223, filed January 21, 2011, and United States Provisional Application No. 61/443,157, filed February 15, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for SENG GUAN CHOW

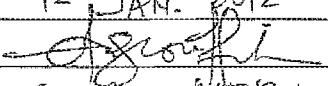
Witnessed on this date:

Signature of Witness:

Printed Name of Witness:

Address of Witness:

12 JAN. 2012



DIOSCOPO MERIUS

5 YISHUN STREET 23

SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JIANMIN FANG of The People's Republic of China, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER DISPOSED OVER THE SEMICONDUCTOR DIE FOR STRESS RELIEF, which is described, illustrated, and claimed in United States Application No. 13/333,739, filed December 21, 2011, United States Provisional Application No. 61/435,223, filed January 21, 2011, and United States Provisional Application No. 61/443,157, filed February 15, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).


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 Jan. 5, 2012
Signature for JIANMIN FANG

Witnessed on this date: Jan. 5, 2012
Signature of Witness: 
Printed Name of Witness: Zekua Ma
Address of Witness: 188 Huaxu Road, Dingpu District
201702 Shanghai China

ASSIGNMENT AND AGREEMENT

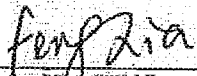
For good and valuable consideration, the receipt of which is hereby acknowledged, I, XIA FENG of The People's Republic of China, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER DISPOSED OVER THE SEMICONDUCTOR DIE FOR STRESS RELIEF, which is described, illustrated, and claimed in United States Application No. 13/333,739, filed December 21, 2011, United States Provisional Application No. 61/435,223, filed January 21, 2011, and United States Provisional Application No. 61/443,157, filed February 15, 2011, together with the entire right, title and interest in and to the applications, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for XIA FENG

Witnessed on this date: Jan 6, 2010

Signature of Witness: 马寅华

Printed Name of Witness: Zehua Ma

Address of Witness: 188 Huaxu Road Qiypu District
201702 Shanghai, PRC

PATENT